



500.40269X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HABA et al.

FEB 24 2004

Serial No.: 09/888,642

Filed: June 26, 2001

For: ELECTRIC COPPER PLATING LIQUID AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR INTEGRATED CIRCUIT
DEVICE USING SAME

Art Unit: 1753

Examiner: E. Wong

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 17, 2004

Sir:

In response to the Office Action mailed October 16, 2003, please amend the
above-identified application as listed in the following, and as set forth on the
following pages:

Amendments to the Specification;

Amendments to the Claims; and

Remarks are included following the amendments.